

Title (en)  
MATERIAL COMPRISING A STACK WITH A THIN ZINC-BASED OXIDE DIELECTRIC UNDERLAYER AND METHOD FOR DEPOSITING THIS MATERIAL

Title (de)  
MATERIAL MIT EINEM STAPEL MIT EINER DÜNNEN DIELEKTRISCHEN UNTERSCHICHT AUS ZINKBASIERTEM OXID UND VERFAHREN ZUR ABLAGERUNG DIESES MATERIALS

Title (fr)  
MATÉRIAU COMPORTANT UN EMPILEMENT A SOUS-COUCHE DIELECTRIQUE FINE D'OXIDE A BASE DE ZINC ET PROCÉDÉ DE DÉPÔT DE CE MATÉRIAU

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Application  
**EP 21732400 A 20210428**

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Abstract (en)  
[origin: WO2021219961A1] The invention relates to a material comprising a substrate (30) coated on one face (29) with a stack of thin layers (14) comprising at least one metallic functional layer (140) and comprising: - an underlayer of zinc-based oxide, ZnO (129), of between 0.3 and 4.4 nm; - a dielectric underlayer of titanium-based oxide, TiOx (127), which is located under and in contact with said underlayer of zinc-based oxide, ZnO (129), with a physical thickness of the dielectric underlayer of titanium-based oxide TiOx (127) of between 5.0 and 50.0 nm; - an overlayer of zinc-based oxide, ZnO (161), of between 2.0 and 10.0 nm; - a dielectric overlayer (165).

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